PRODUCT / PROCESS CHANGE INFORMATION

New Tape Header finishing procedure for EEPROM in WLCSP (packed with EPE foam)

What is the change?

ST is modifying the Tape Header finishing procedure of its WLCSP assembled at STATSChipPAC (Singapore):

- In the **current situation**, the **header is linked to the EPE foam**, which is linked to the protective belt. Then placing (at finishing step) or removing (at customer unreeling step) the protective belt could induce tension to the tape.
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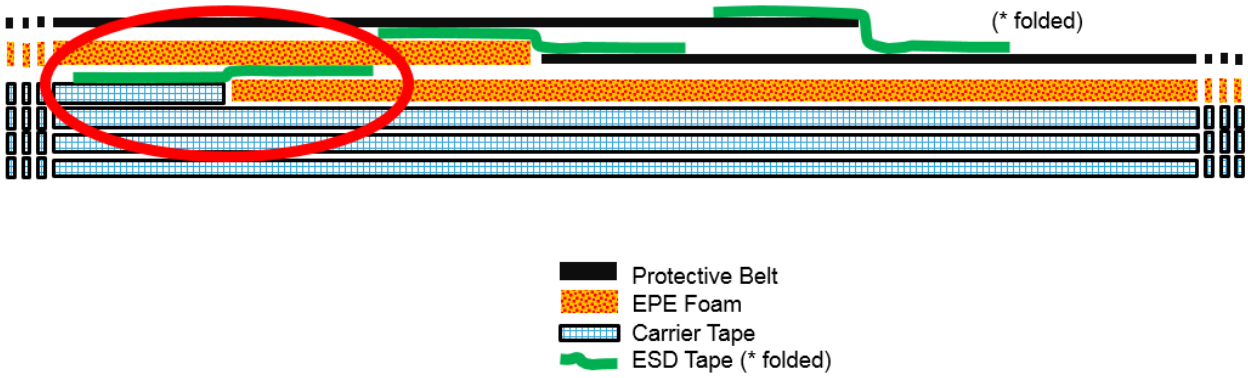
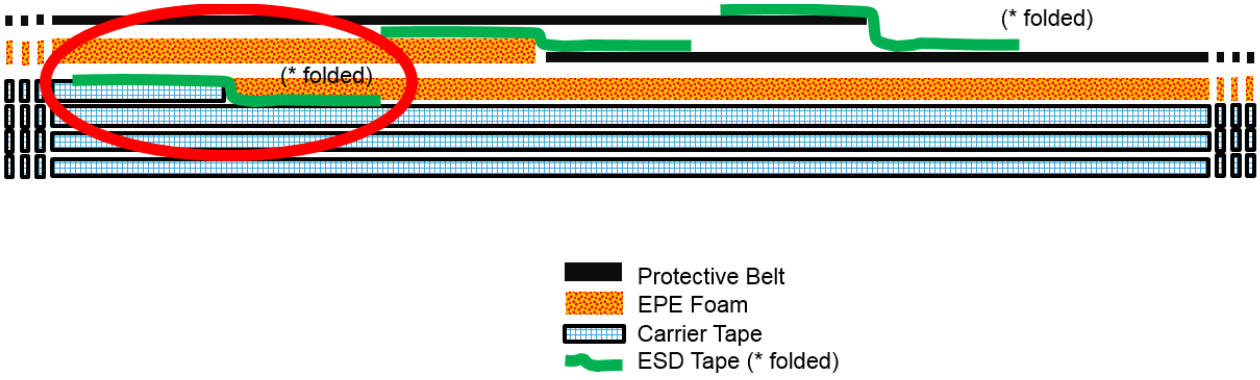


- With the **new procedure**, the header is **pasted to itself** (with ESD tape). The EPE foam is put in place and pasted to the protective belt. Then, the protective belt and the header being independent, removing the protective belt will have no action on the tape.



Why?

With the **new procedure**, placing or removing the protective belt will avoid potential tension to the tape at STATSChipPAC finishing or at unreeling step at customer.

When?

New procedure for tape header finishing for all EEPROM WLCSP products will start from beginning of December 2017.

How will the change be qualified?

The **qualification** of this **new procedure** has been performed using the standard ST Microelectronics Corporate Procedures for Quality & Reliability and the Best Known Method (BKM) defined for WLCSP finishing.

What is the impact of the change?

- **Form, Fit, Function:** No change

Appendix A: Product Change Information

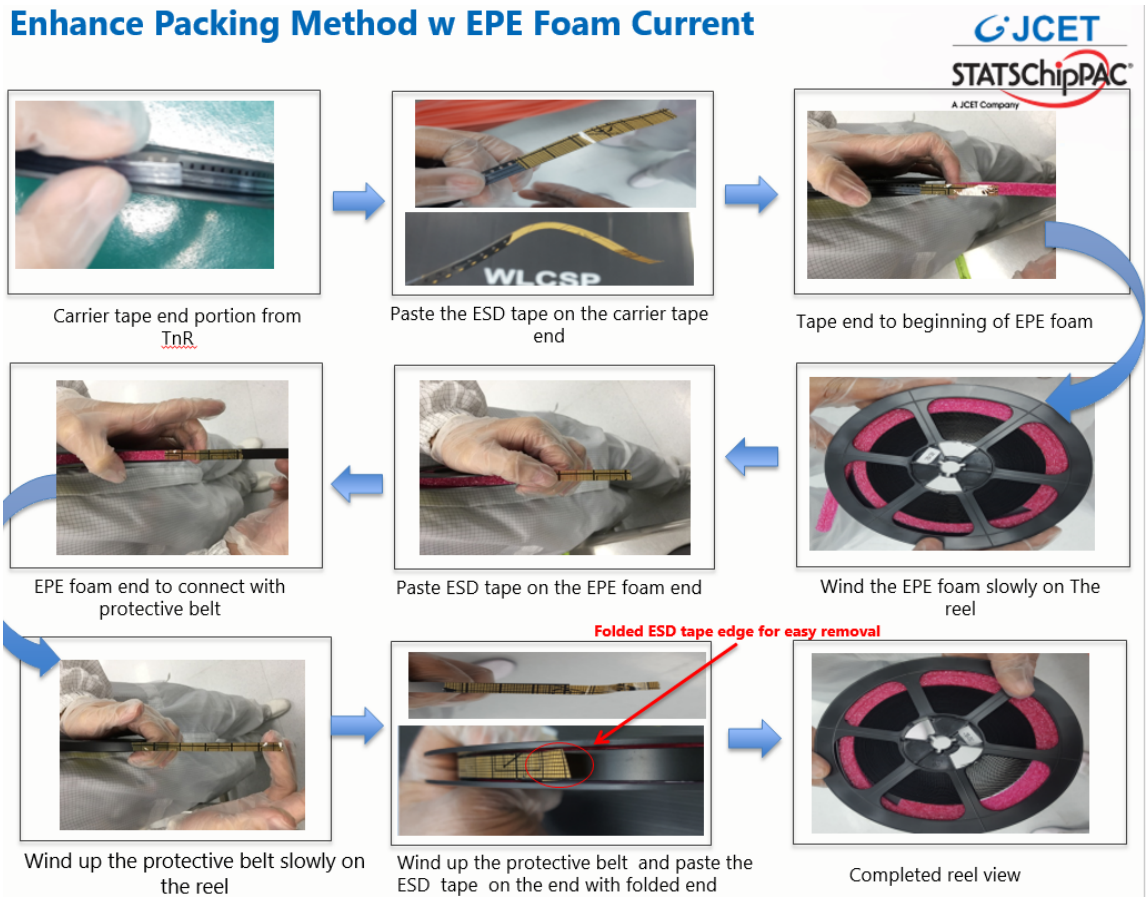
Product family / Commercial products:	EEPROM WLCSP
Customer(s):	All
Type of change:	New procedure for End of Tape (header) finishing
Reason for the change:	Quality improvement
Description of the change:	New “End of Tape” procedure for EEPROM WLCSP finishing at STATSChipPAC (Singapore)
Forecast date of the change: (Notification to customer)	Week 47 / 2017
Forecast date of Qualification samples availability for customer(s):	N/A
Product Line(s) and/or Part Number(s):	See APPENDIX B
Estimated date of first shipment:	Week 50 / 2017

Appendix B: Concerned Commercial Part Numbers:

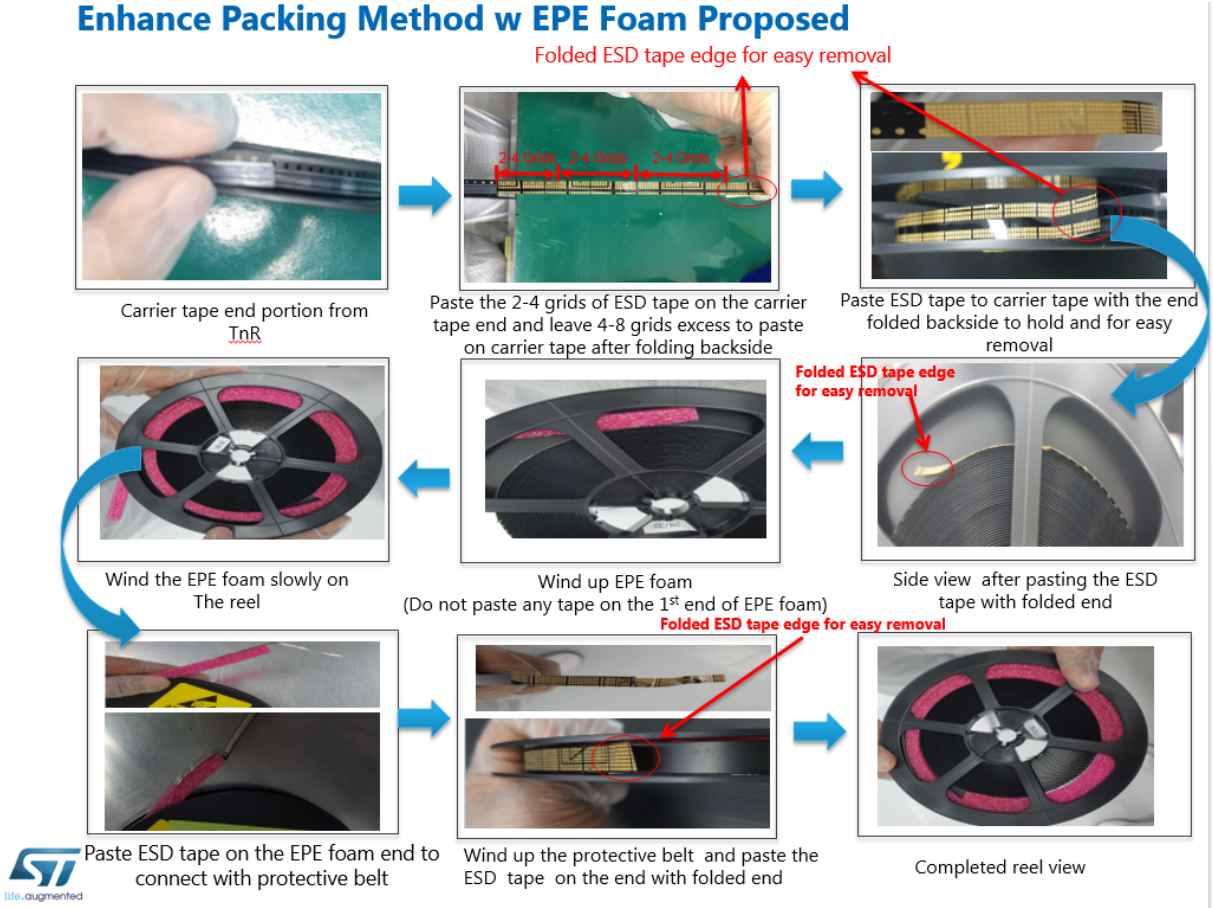
M24C64S-FCU6T/TF
M24C32S-FCU6T/T
M24128S-FCU6T/TF
M24C32S-FCU6T/TF
M24128S-FCU6T/T
M24C64S-FCU6T/T
M24128-DFCS6TP/K
M95128-DFCS6TP/K
M24M01-DFCS6TP/K
M95M01-DFCS6TP/K
M24M01-RCS6TP/A
M24256-DFCS6TP/K
M95256-DFCS6TP/K
M24M02-DRCS6TP/K
M95M02-DRCS6TP/K
M24512-DFCS6TP/K
M95512-DFCS6TP/K
M24C08-FCS5TP/S
M24C16-FCS5TP/S
M24C16-DFCU6TP/K
M24C64-FCS6TP/K
M24C64-DFCT6TP/K
M95160-RCS6TP/S

New Tape Header finishing procedure
for EEPROM in WLCSP (packed with EPE foam)

Enhance Packing Method w EPE Foam Current



Enhance Packing Method w EPE Foam Proposed



Document Revision History

Date	Rev.	Description of the Revision
Oct. 26, 2017	1.00	First draft creation – Christian POLI

Source Documents & Reference Documents

Source document Title	**Rev.:**	**Date:**